



X CLOSE

Dual-in-line Package Type Switch > SSGM Series > SSGM740101

2 to 10 Circuits-designed Type SSGM Series

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Part number [Series Common Info](#)
SSGM740101

NET SHOP

3D CAD

RoHS

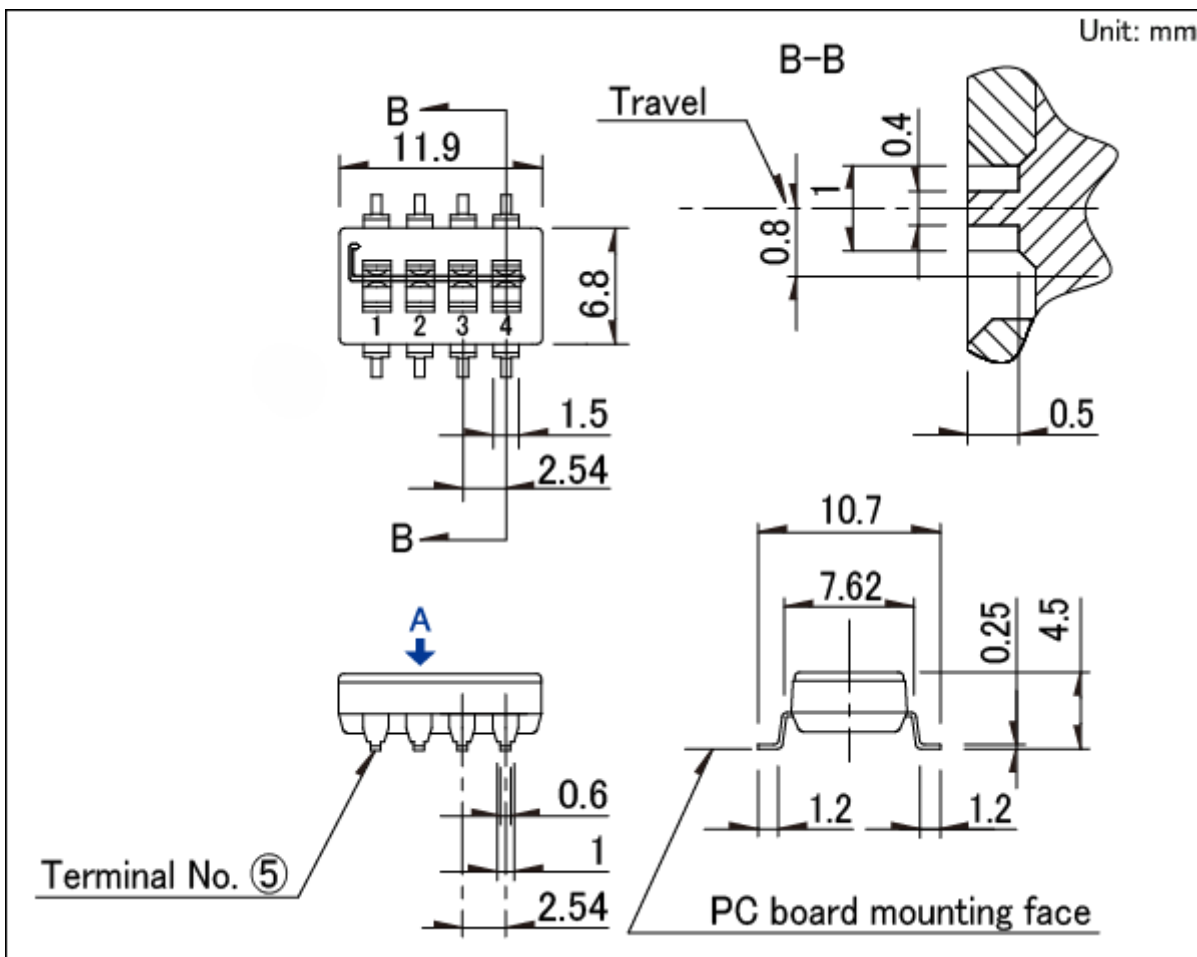
Print

Inquiry

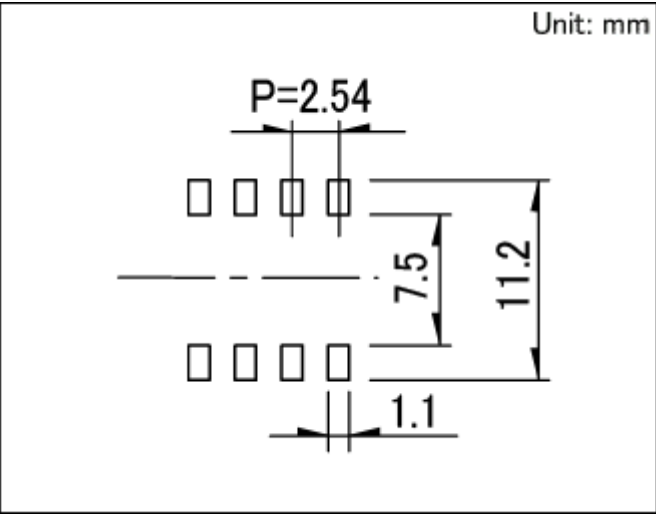
Soldering	Reflow
Actuator configuration	Flat
Operating force	3.5 ± 2.5N
Packaging style	Taping
Poles	4
Operating temperature range	-40°C to +85°C
	25mA 24V DC (at opening and closing)
Ratings (max.)/(min.) (Resistive load)	0.1A 50V DC (when energized)
	50 μ A 3V DC

Electrical performance	Contact resistance (Initial performance/After lifetime)	50mΩ max./100mΩ max.
	Insulation resistance	100MΩ min. 500V DC
	Voltage proof	500V AC for 1 minute
	Terminal strength	5N for 1 minute
Mechanical performance	Operating direction	10N
	Pulling direction	10N
	Without load	3,000 cycles
Durability	Operating life	With load
		3,000 cycles (25mA 24V DC)
Environmental performance	Cold	-40°C 250h
	Dry heat	85°C 250h
	Damp heat	60°C, 90 to 95%RH 250h
Minimum order unit (pcs.)	Japan	1,000
	Export	4,000

Dimensions

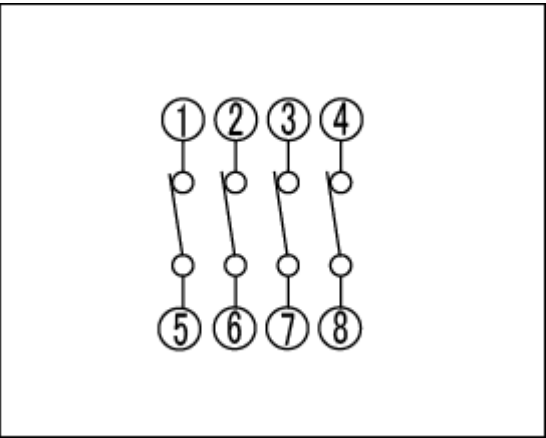


Land Dimensions



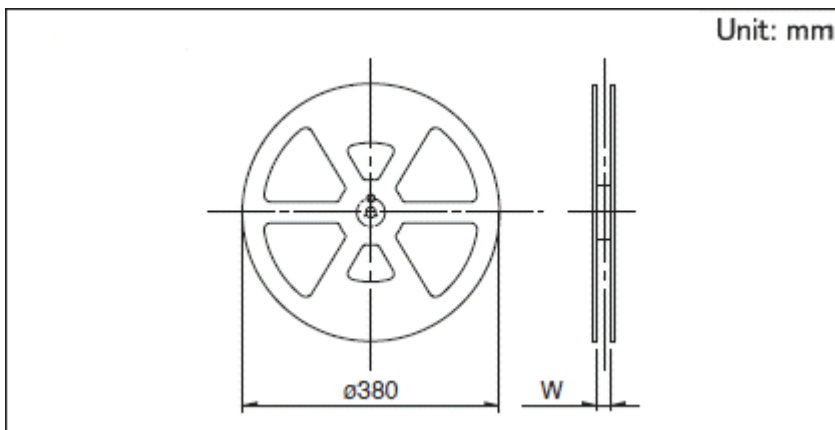
Viewed from direction A in the dimensions.

Circuit Diagram



Packing Specifications

Taping



	1 reel	1,000
Number of packages (pcs.)	1 case / Japan	2,000
	1 case / export packing	4,000
Reel width W(mm)		25.4
Tape width (mm)		24
Export package measurements (mm)	406 × 406 × 190	

Soldering Conditions

Example of Reflow Soldering Condition

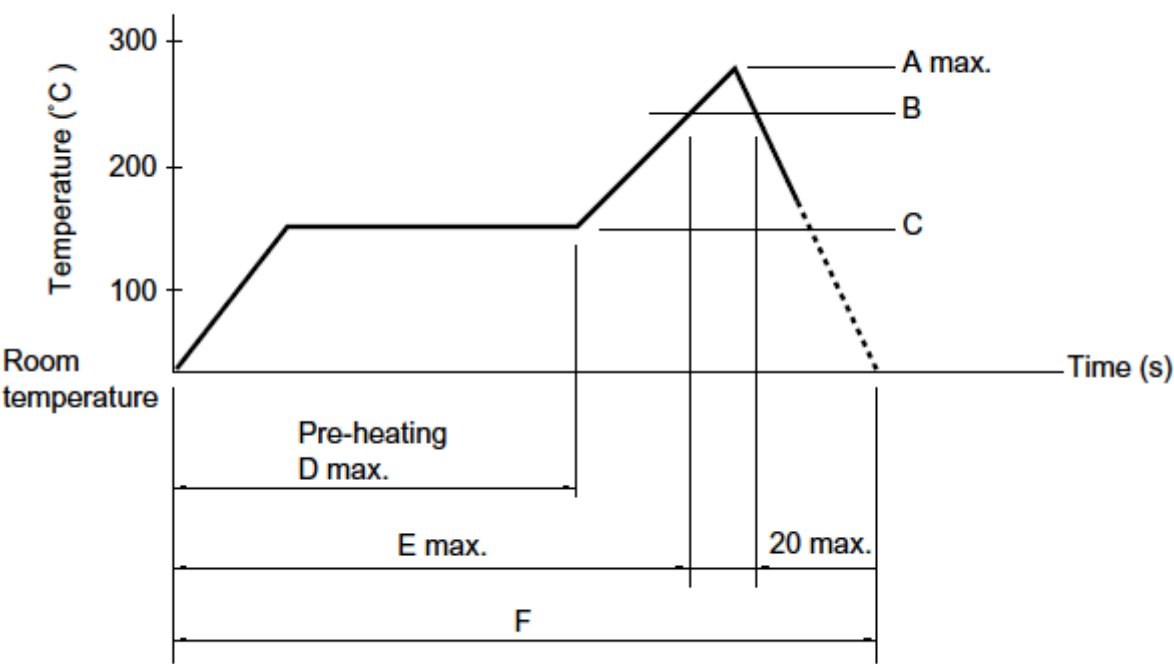
1. Heating method

Double heating method with infrared heater.

2. Temperature measurement

Thermocouple 0.1 to 0.2Φ CA (K) or CC (T) at soldering portion (copper foil surface). A heat resisting tape should be used for fixed measurement.

3. Temperature profile



A(°C)	B(°C)	C(°C)	D(s)	E(s)	F(s)
3s max.					
250	240	150	120	-	-

- (1) The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
- (2) Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Soldering temperature350 ± 5°C

Soldering time 5s max.

Notes are common to this series/models.

1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.
2. Please place purchase orders per minimum order unit (integer).
3. Products other than those listed in the above chart are also available. Please contact us for details.

Inquiries about Products

[Inquiry.](#)

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